

01-19-1999

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To the Honorable Commissioner of Patent

shd original documents or copy thereof.

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1. Name of conveying party(ies):

Hao-Chieh Yung and
Gene Jing-Chiang ChangAdditional name(s) of conveying party(ies) attached? ☐ Yes ☒ No3. Nature of conveyance: *MPD 12-31-98*

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other _____

Execution Date: October 29, 1997

Name of receiving party(ies):

Name: WINBOND ELECTRONICS CORP

Internal Address: _____

Street Address: No. 4, Creation Road III
Science-Based Industrial ParkCity: Hsinchu, Taiwan, R. O. C.
State: _____ ZIP: _____Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: October 29, 1997

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Bo-In Lin

Internal Address: _____

Street Address: 13445 Mandoli DriveCity: Los Altos Hills State: CA ZIP: 940226. Total number of applications and patents involved: One7. Total fee (37 CFR 3.41):..... \$ 40.00☒ Enclosed☐ Authorized to be charged to deposit account

8. Deposit account number: _____

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Ching-lu Lin

Name of Person Signing

Signature

Date

Total number of pages comprising cover sheet:

Three

Docket No. WNEND85153

ASSIGNMENT

INVENTOR
AND CITYWhereas, I, Gene Jing-Chiang Chang of No. 34, Creation Rd. III,
Science Based Industrial Park, Hsinchu, Taiwan, Republic of China

have invented:

TITLE:

PRECISION BREAKING OF SEMICONDUCTOR WAFER INTO CHIPS BY
APPLYING AN ETCH PROCESSDATE INVENTOR
SIGNED THE
DECLARATIONand executed a United States patent application therefor
on October 29, 1997;

Whereas, WINBOND ELECTRONICS CORP. , having a place of
business at HSINCHU, TAIWAN, R.O.C., (hereinafter called
WINBOND), desires to acquire the entire right, title and interest of
said application and invention, and to any United States and
foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof
is hereby acknowledged, I, the above named, hereby sell, assign,
and transfer to WINBOND, its successors and assigns, the entire
right, title and interest in the said application and invention therein
disclosed for the United States and foreign countries, and all rights
of priority resulting from the filing said United States application,
and I request the Commissioner of Patents to issue any Letters
Patent granted upon the inventions set forth in said application to
WINBOND its successors and assigns; and I hereby agree that
WINBOND may apply for foreign Letters Patent on said invention
and I will execute all papers necessary in connection with the
United States and foreign applications when called upon to do so by

CITY AND
DATESigned and Sealed at Hsinchu, Taiwan, R.O.C.
on Oct. 29, 1997.

Gene Jing-Chiang Chang
SIGNATURE OF INVENTOR

Docket No. WNBND85153

ASSIGNMENT

INVENTOR
AND CITYWhereas, I, **Hao-Chieh Yung** of No. 34, Creation Rd. III,
Science Based Industrial Park, Hsinchu, Taiwan, Republic of China

have invented:

TITLE:

**PRECISION BREAKING OF SEMICONDUCTOR WAFER INTO CHIPS BY
APPLYING AN ETCH PROCESS**DATE INVENTOR
SIGNED THE
DECLARATION

and executed a United States patent application therefor

on October 29
July, 1997;

Whereas, WINBOND ELECTRONICS CORP. , having a place of business at HSINCHU, TAIWAN, R.O.C., (hereinafter called WINBOND), desires to acquire the entire right, title and interest of said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, I, the above named, hereby sell, assign, and transfer to WINBOND, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing said United States application, and I request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said application to WINBOND its successors and assigns; and I hereby agree that WINBOND may apply for foreign Letters Patent on said invention and I will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by

CITY AND
DATESigned and Sealed at Hsinchu, Taiwan, R.O.C.
on Oct. 29, 1997.

Hao - Chieh Yung
SIGNATURE OF INVENTOR